

NOTES :

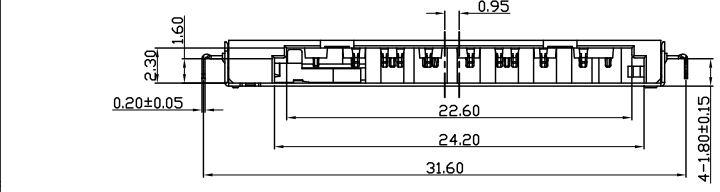
- MATERIAL :
 - HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
 - SHELL:STAINLESS STEEL SUS304.
 - CONTACT:PHOSPHER BRONZE C5210.
 - SLIDER:LCP S475 UL94 V-0, BLACK COLOR.
 - SPRING:HARD STEEL SWP-B.
 - LINK:STAINLESS STEEL SUS304.
- FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u"MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30U" MIN SOLDERABLE NICKEL PLATED OVER ALL.
- ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

RECOMMENDED PCB LAYOUT
(ALL TOLERANCE ARE ±0.05)

PAD AREA

PART.NO.:
TW199-AP401-**

- 42: 功能区镀金1U", 锡脚镀雾纯锡至少100U"
- 43: 功能区镀金3U", 锡脚镀雾纯锡至少100U"
- 44: 功能区镀金5U", 锡脚镀雾纯锡至少100U"
- 45: 功能区镀金10U", 锡脚镀雾纯锡至少100U"
- 46: 功能区镀金15U", 锡脚镀雾纯锡至少100U"
- 47: 功能区镀金30U", 锡脚镀雾纯锡至少100U"



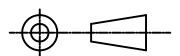
with out card	CD		CD
	WP		WP
inserted card (unlock)	CD		CD
	WP		WP
inserted card(lock)	CD		CD
	WP		WP

GENERAL TOLERANCE		DWG.NO.	TW199-AP401-00	PART.NO.	TW199-AP401-**	DRAWN	L.M.J 2019.06.21
x.±0.50	x. °±5 °	REV.	A	TITLE	SD7.0 Push反向沉板1.80 CONN	CHECKED	
.x±0.25	.x °±2 °	SIZE		SHEET	1 OF 3	APPROVED	
.xx±0.15	.xx °±1 °	A4					

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			

PIN DESCRIPTION

PIN	SD	UHS-II	MMC	EXPRESS
	DESCRIPTION	DESCRIPTION	DESCRIPTION	DESCRIPTION
P1	CD/DATA3		RSV	PERST#
P2	CMD		CMD	
P3	VSS1	VSS1	VSS1	
P4	VDD	VDD1	VDD	VDD1
P5	CLK		CLK	
P6	VSS2	VSS2	VSS2	
P7	DAT0	RCLK+	DAT	REFCLK+
P8	DAT1	RCLK-		REFCLK-
P9	DAT2			CLKREQ#
P10		VSS3		VSS3
P11		D0+		PC1e TX+
P12		D0-		PC1e TX-
P13		VSS4		VSS4
P14		VDD2		VDD2
P15		D1-		PC1e RX-
P16		D1+		PC1e RX+
P17		VSS5		VSS5
P18				VDD3
CD	CARD DETECT	CARD DETECT	CARD DETECT	CARD DETECT
WP	WRITE PROTECT	WRITE PROTECT		WRITE PROTECT

GENERAL TOLERANCE	DWG.NO.	TW199-AP401-00	PART.NO.	TW199-AP401-***	DRAWN	L.M.J 2019.06.21
.x±0.50	REV.	A	TITLE	SD7.0 Push反向沉板1.80 CONN	CHECKED	
.x±0.25	SIZE		SHEET	2 OF 3	APPROVED	
.xx±0.15	A4					

UNIT	mm	SCALE	1:1
 OLN 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			

东莞市欧联电子科技有限公司

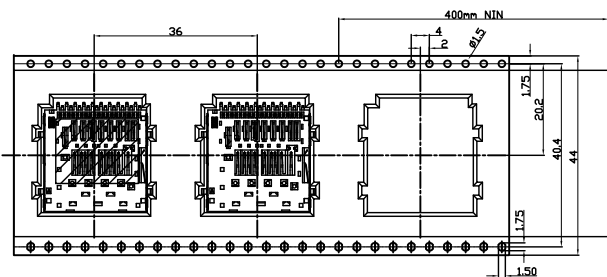
包装作业规范

REV.	ECN.NO.	MODIFY.CONTENT
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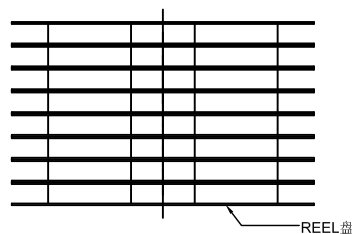
包装作业图示及说明

(PACKING OPERATION DIAGRAM & INSTRUCTION)

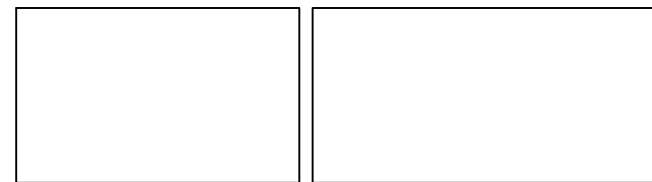
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
 - 2) 包装时,如图所示.
 - 3) 一个REEL包装盘放置300个成品.



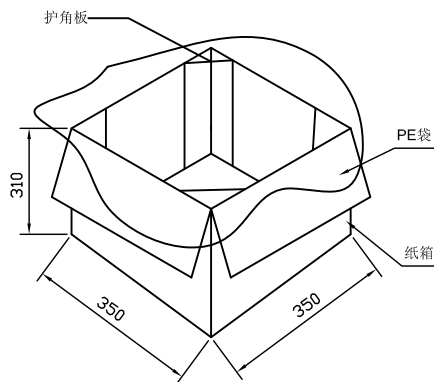
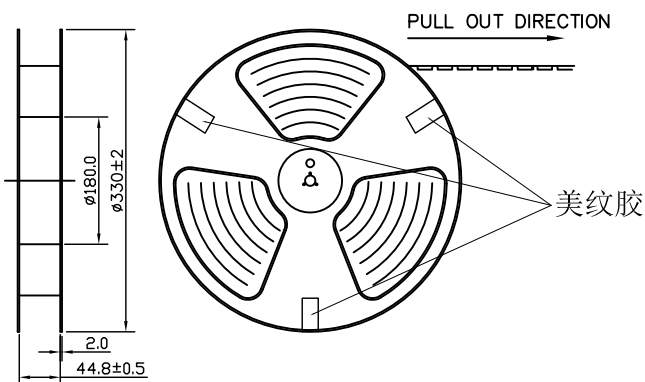
- 三.
- 1) 每箱装 6 盘REEL包装盘.
 - 2) 每箱放置 1800 PCS 的成品.



- 四.
- 1) 用TAPE将纸箱封实.


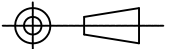


- 二.
- 1) 装盘前先把前面空20pcs产品,然后再开始装盘, 尾端也需空10pcs产品,自粘带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿.

GENERAL TOLERANCE		DWG.NO.	TW199-AP401-00	PART.NO.	TW199-AP401-**	DRAWN	L.M.J 2019.06.21	UNIT	mm	SCALE	1:1
x. ± 0.50	x. $\pm 5^\circ$	REV.	A	TITLE	SD7.0 Push反向沉板1.80 CONN	CHECKED		 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x ± 0.25	.x $\pm 2^\circ$	SIZE		SHEET	3 OF 3	APPROVED					
.xx ± 0.15	.xx $\pm 1^\circ$	A4									